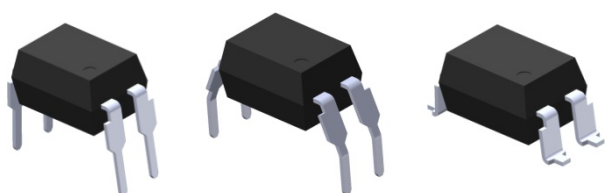
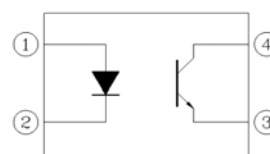


## 4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER EL817-G Series



Schematic



### Features:

- Halogens free.
- Current transfer ratio (CTR: 50~600% at  $I_F = 5\text{mA}$ ,  $V_{CE} = 5\text{V}$ )
- High isolation voltage between input and output (Viso=5000 V rms )
- Creepage distance >7.62 mm
- Operating temperature up to +110°C
- Compact small outline package
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved
- CQC approved

### Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

### Description

The EL817-G series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector encapsulated with green compound. The devices are in a 4-pin DIP package and available in wide-lead spacing and SMD option.

### Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

**Absolute Maximum Ratings (Ta=25°C)**

	Parameter	Symbol	Rating	Unit
Input	Forward current	$I_F$	60	mA
	Peak forward current (1us, pulse)	$I_{FP}$	1	A
	Reverse voltage	$V_R$	6	V
	Power Dissipation		$P_D$	100
2.9				mW/°C
Output	Break Down Voltage	$P_C$	150	mW
			5.8	mW/°C
	Collector current	$I_C$	50	mA
	Collector-Emitter voltage	$V_{CEO}$	80	V
	Emitter-Collector voltage	$V_{ECO}$	7	V
Total Power Dissipation	$P_{TOT}$	200	mW	
Isolation Voltage* <sup>1</sup>	$V_{ISO}$	5000	V rms	
Operating Temperature	$T_{OPR}$	-55 to 110	°C	
Storage Temperature	$T_{STG}$	-55 to 125	°C	
Soldering Temperature* <sup>2</sup>	$T_{SOL}$	260	°C	

Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

\*2 For 10 seconds

**Electro-Optical Characteristics (Ta=25°C unless specified otherwise)**

**Input**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	$V_F$	-	1.2	1.4	V	$I_F = 20\text{mA}$
Reverse Current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 4\text{V}$
Input capacitance	$C_{in}$	-	30	250	pF	$V = 0, f = 1\text{kHz}$

**Output**

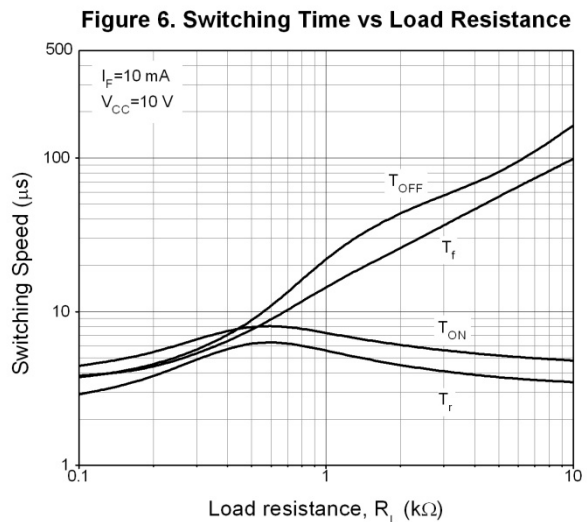
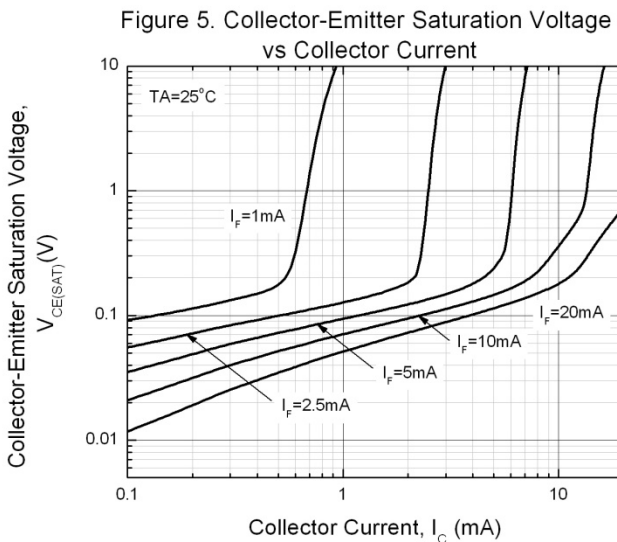
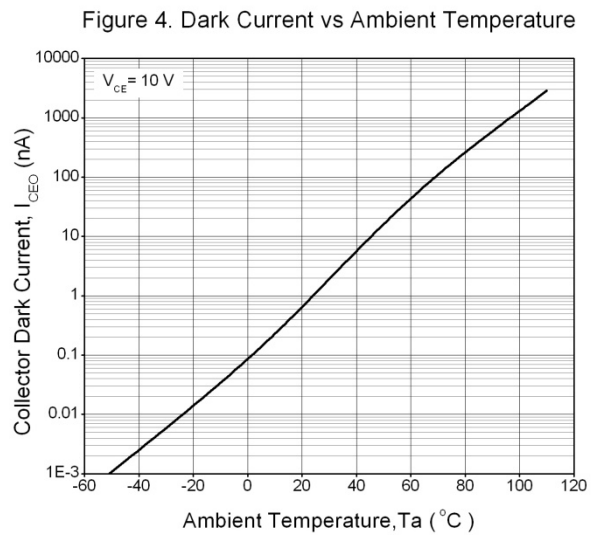
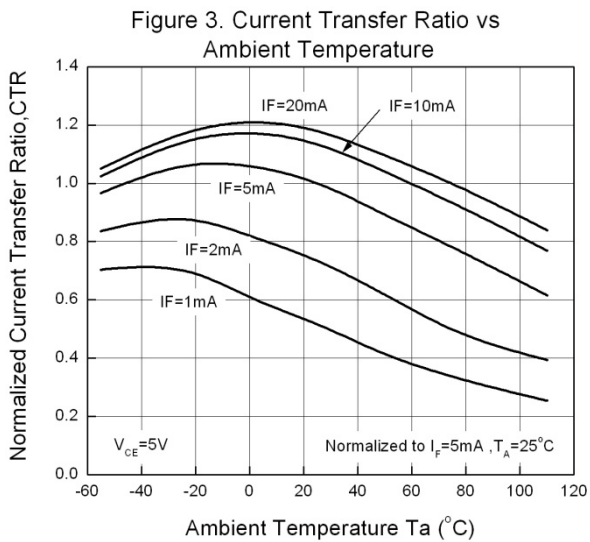
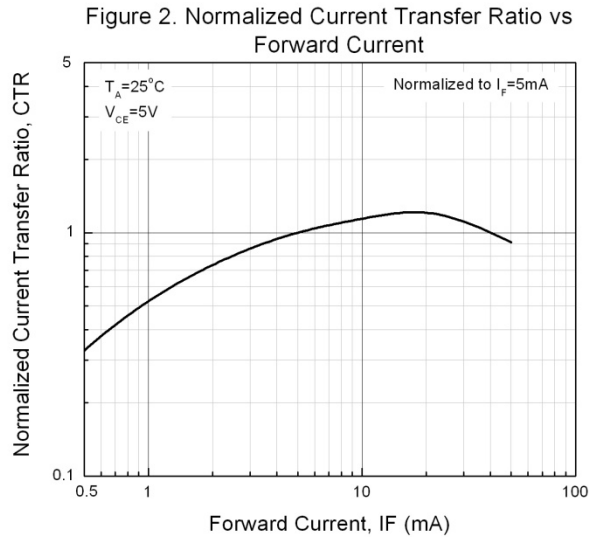
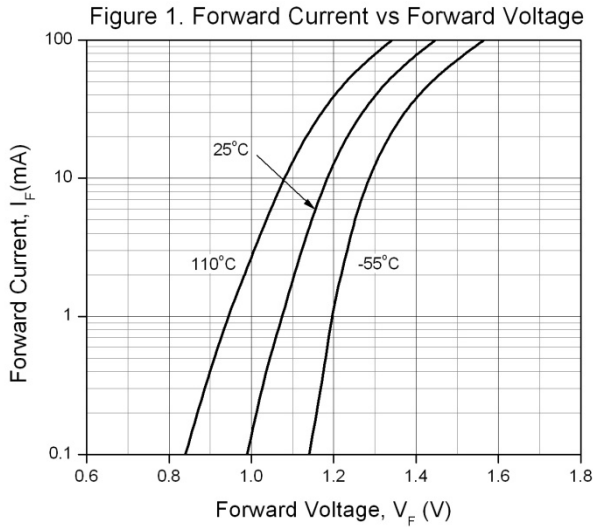
Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	$I_{CEO}$	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	$BV_{CEO}$	80	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	$BV_{ECO}$	7	-	-	V	$I_E = 0.1\text{mA}$

**Transfer Characteristics**

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	EL817	50	-	600	%	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$
	EL817A	80	-	160		
	EL817B	130	-	260		
	EL817C	200	-	400		
	EL817D	300	-	600		
	EL817X	100	-	200		
	EL817Y	150	-	300		
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_F = 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	$R_{IO}$	$5 \times 10^{10}$	-	-	$\Omega$	$V_{IO} = 500\text{Vdc}, 40\sim 60\% \text{ R.H.}$
Floating capacitance	$C_{IO}$	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	$f_c$	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Rise time	$t_r$	-	6	18	$\mu\text{s}$	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	$t_f$	-	8	18	$\mu\text{s}$	

\* Typical values at  $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves



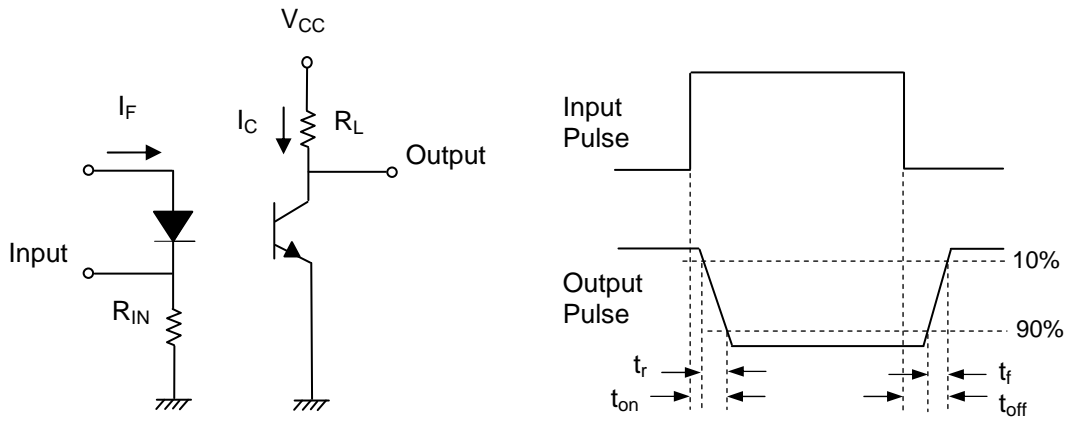


Figure 7. Switching Time Test Circuit & Waveforms

**Order Information**

**Part Number**

**EL817X(Y)(Z)-FVG**

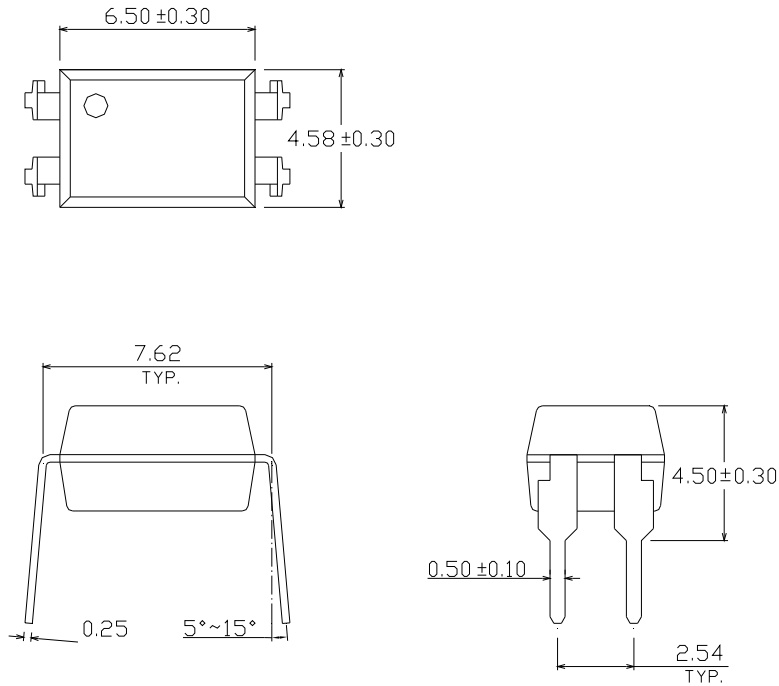
**Note**

- X = Lead form option (S, S1, S2, M or none)
- Y = CTR Rank (A, B, C, D, X, Y or none)
- Z = Tape and reel option (TA, TB, TU, TD or none).
- F = Lead frame option (F: Iron, None: copper)
- V = VDE safety (optional).
- G = Halogens free

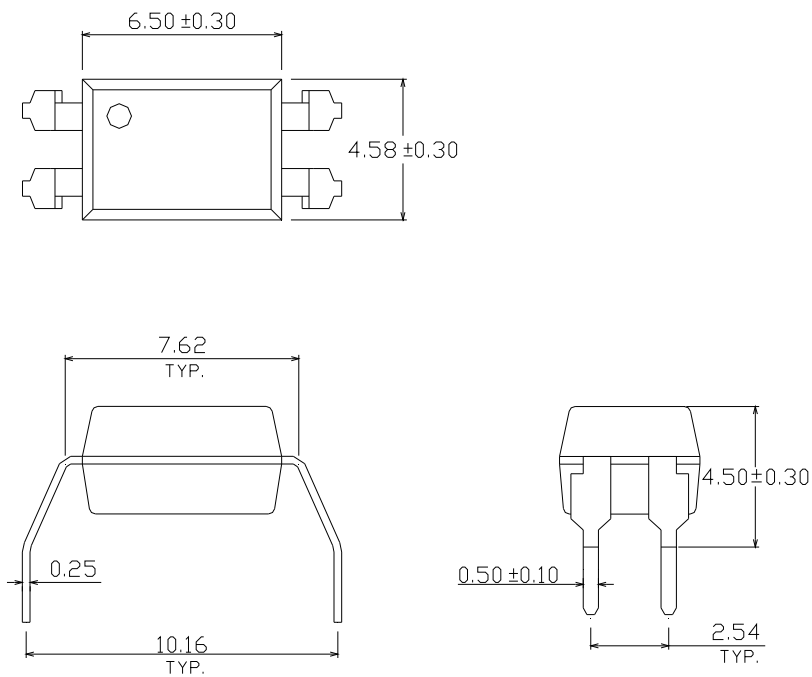
Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel
S2 (TA)	Surface mount lead form (Gull-wing) + TA tape & reel option	500 units per reel
S2 (TB)	Surface mount lead form (Gull-wing) + TB tape & reel option	500 units per reel
S (TU)	Surface mount lead form + TU tape & reel option	1500 units per reel
S (TD)	Surface mount lead form + TD tape & reel option	1500 units per reel
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel

Package Dimension (Dimensions in mm)

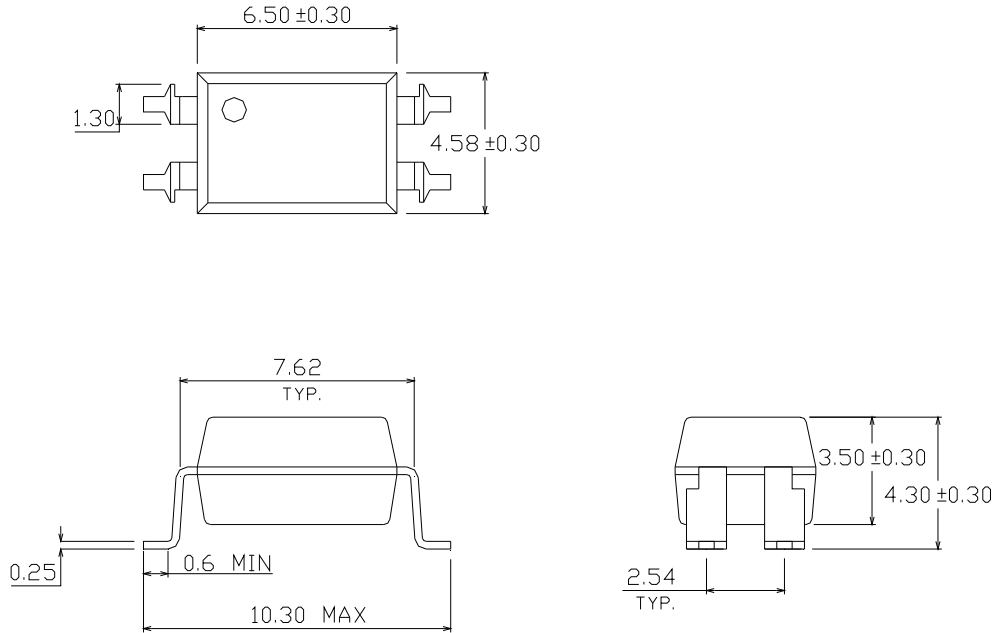
Standard DIP Type



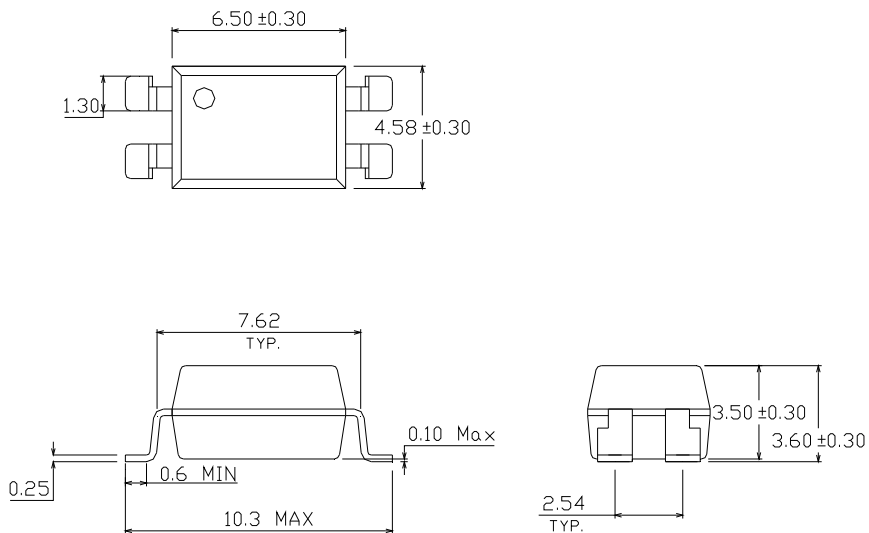
Option M Type



Option S Type

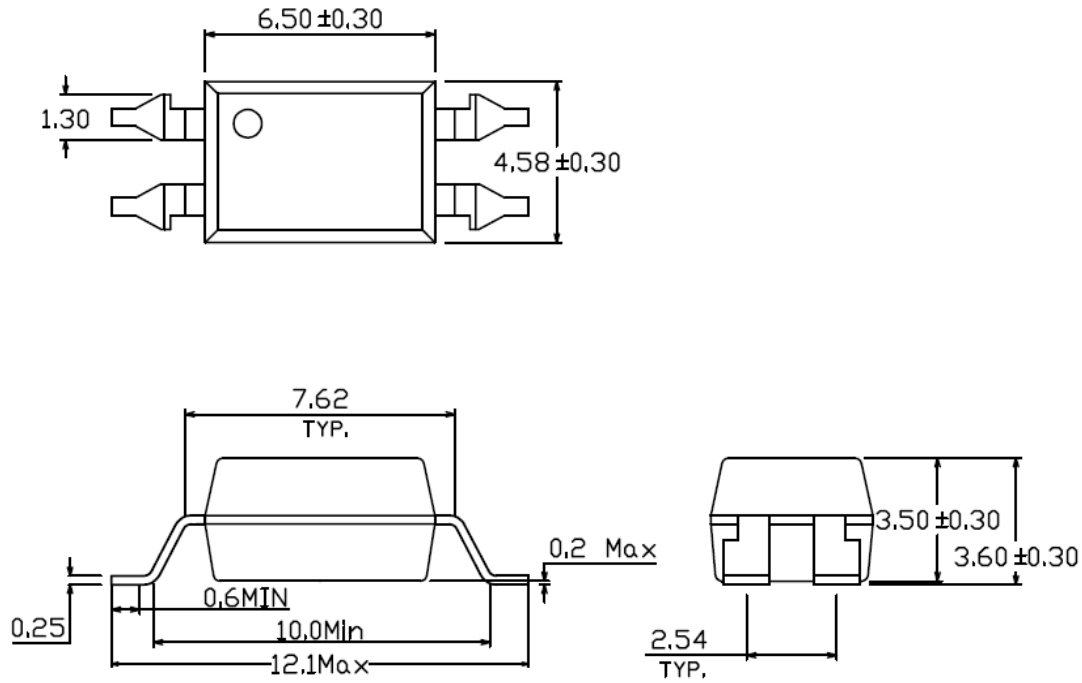


Option S1 Type





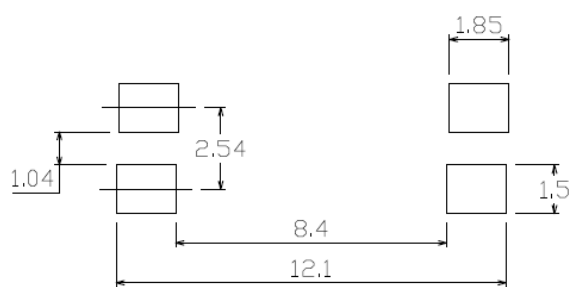
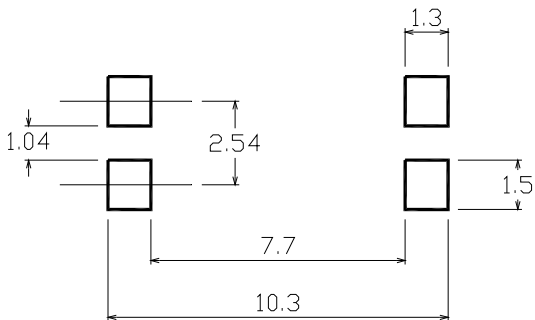
**Option S2 Type**



**Recommended pad layout for surface mount leadform**

**For S and S1 option**

**For S2 option**



## Device Marking

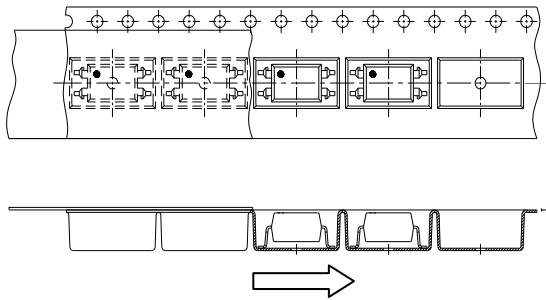


## Notes

EL	denotes EVERLIGHT
817	denotes Device Number
R	denotes CTR Rank (A, B, C, D or none)
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

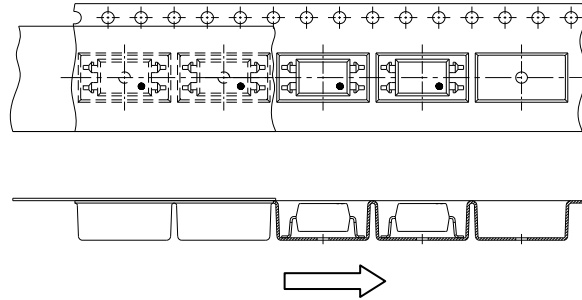
### Tape & Reel Packing Specifications

**Option TA**



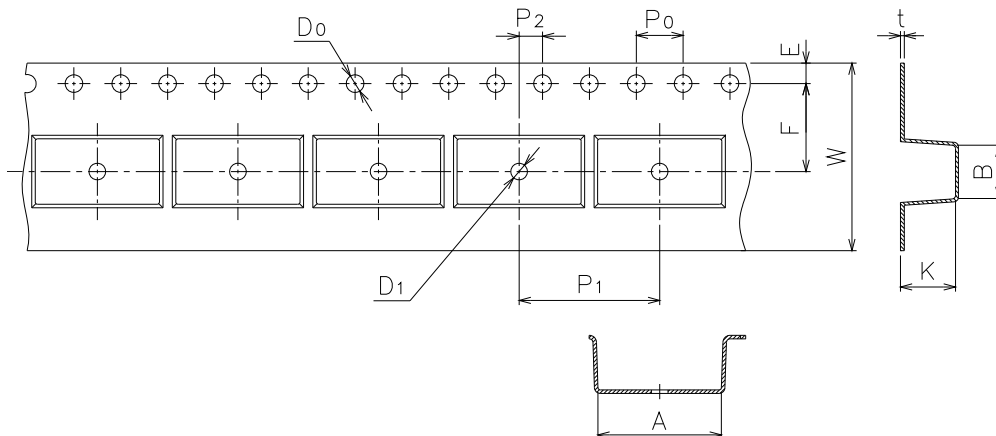
Direction of feed from reel

**Option TB**



Direction of feed from reel

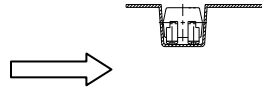
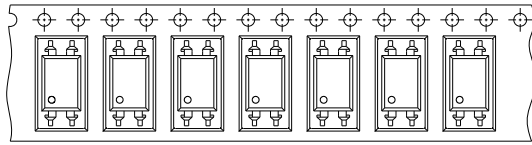
### Tape dimensions



### Tape dimensions

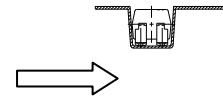
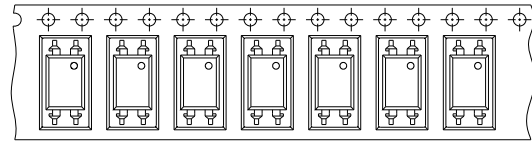
Dimension No.	<b>A</b>	<b>B</b>	<b>Do</b>	<b>D1</b>	<b>E</b>	<b>F</b>
Dimension (mm)	10.5±0.1	4.65±0.1	1.55±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension (mm) S2	12.15±0.1	4.65±0.1	1.55±0.1	1.50±0.1	1.75±0.1	7.5±0.1
Dimension No.	<b>Po</b>	<b>P1</b>	<b>P2</b>	<b>t</b>	<b>W</b>	<b>K</b>
Dimension (mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.35±0.1	16.0±0.3	4.75±0.1
Dimension (mm) S2	4.0±0.1	16.0±0.1	2.0±0.1	0.35±0.1	16.0±0.3	3.90±0.1

**Option TD**



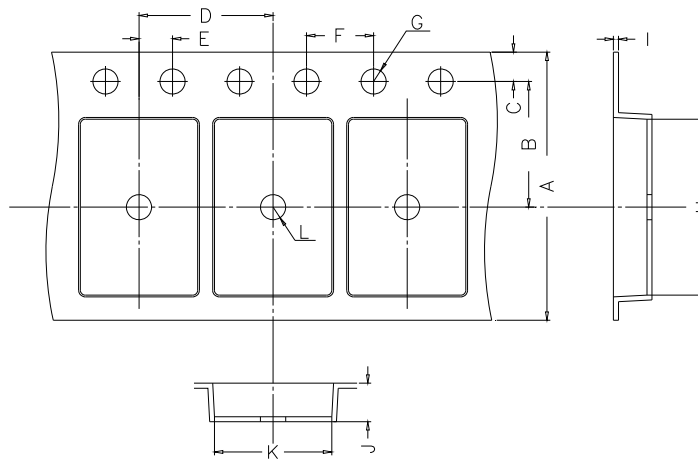
Direction of feed from reel

**Option TU**



Direction of feed from reel

**Tape dimensions**

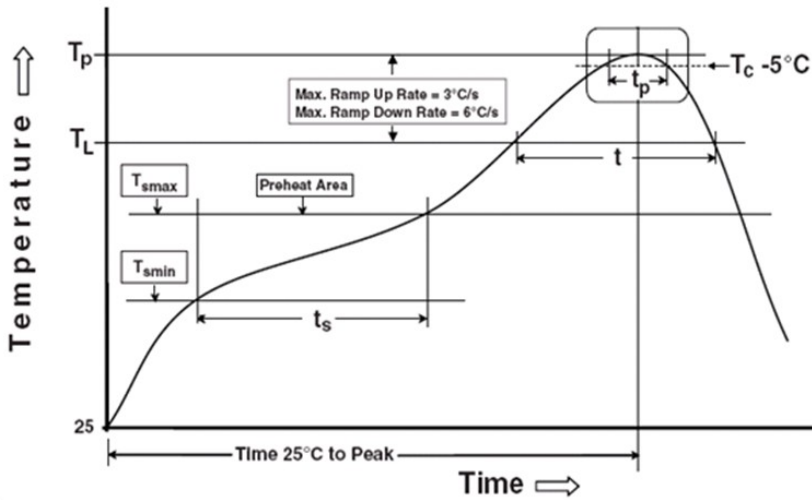


Dimension No.	<b>A</b>	<b>B</b>	<b>C</b>	<b>D</b>	<b>E</b>	<b>F</b>
Dimension(mm)	16.00±0.3	7.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1
Dimension No.	<b>G</b>	<b>H</b>	<b>I</b>	<b>J</b>	<b>K</b>	<b>L</b>
Dimension(mm)	1.55±0.05	10.4±0.1	0.4±0.05	4.60±0.1	5.1±0.1	1.55±0.05

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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